Bill of Materials

	SCK1	SK3	Remarks
Core Material	Kinsus/Samsung BT/HL-832	Kinsus/Samsung BT/HL-832	Same BOM
Die Attach	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach)	Ablestik 2025D (bottom die) Loctite/Hysol QMI536 (spacer) Ablestik 2025M (top die) Ablestik 2000 (Die Attach) Hereaus 96.5Sn/3.5Ag (Discrete Component Attach)	
Wire type	Gold MKE R 2N	Gold MKE R 2N	
Mold Compound	Sumitomo EME-G770LC Sumitomo EME-G760C	Sumitomo EME-G770LC Sumitomo EME-G760C	
Lead Finish	Sn/Ag/Cu =96.5/3.0/0.5	Sn/Ag/Cu =96.5/3.0/0.5	

Assembly Transfer of Select CSP_BGA Products to STATS ChipPAC Korea Plant3

Qualification Plan Summary of CSP_BGA at STATS ChipPAC Korea Plant3

QUALIFICATION PLAN			
TEST	**SPECIFICATION**	**SAMPLE SIZE**	**EXPECTED COMPLETION DATE**
Temperature Cycle (TC)*	JEDEC *JESD22-A104*	3 x 32	February 2015
Unbiased Highly Accelerated Stress Test (uHAST)*	JEDEC *JESD22-A118*	3 x 32	February 2015
Solder Heat Resistance (SHR)*	JEDEC/IPC *J-STD-020*	3 x 11	February 2015
Electrostatic Discharge *Field Induced Charge Device Model*	JEDEC *JESD22-C101*	3/voltage	February 2015

*Preconditioned per JEDEC/IPC J-STD-020